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| DB=U | SPT; PLUR=YES; OP=ADJ | | |
| <u>L3</u> | L2 and trench | 7 | <u>L3</u> |
| <u>L2</u> | L1 and (polysilicon near2 fill) | 7 | <u>L2</u> |
| <u>L1</u> | jfet and mosfet | 1343 | <u>L1</u> |

END OF SEARCH HISTORY

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Search Results - Record(s) 1 through 7 of 7 returned.

1. Document ID: US 6707095 B1

L3: Entry 1 of 7

File: USPT

Mar 16, 2004

US-PAT-NO: 6707095

DOCUMENT-IDENTIFIER: US 6707095 B1

TITLE: Structure and method for improved vertical MOSFET DRAM cell-to-cell

isolation

Full Title Ctation Front Review Classification Oate Reference Claims NMC Draws D.

1. 2. Document ID: US 6576516 B1

L3: Entry 2 of 7 File: USPT Jun 10, 2003

US-PAT-NO: 6576516

DOCUMENT-IDENTIFIER: US 6576516 B1

TITLE: High voltage power $\underline{\text{MOSFET}}$ having a voltage sustaining region that includes doped columns formed by $\underline{\text{trench}}$ etching and diffusion from regions of oppositely doped polysilicon

Eull: Title: Citation: Front Review Classification Date Reference

Claims KNMC Draw De

3. Document ID: US 6441422 B1

L3: Entry 3 of 7

File: USPT

Aug 27, 2002

US-PAT-NO: 6441422

DOCUMENT-IDENTIFIER: US 6441422 B1

TITLE: Structure and method for ultra-scalable hybrid DRAM cell with contacted P-

well

Full Title Citation Front Review Classification Date Reference Citation Claims KMC Draw De

4. Document ID: US 6291298 B1

L3: Entry 4 of 7

File: USPT

Sep 18, 2001

US-PAT-NO: 6291298

Record List Display Page 2 of 3

DOCUMENT-IDENTIFIER: US 6291298 B1

TITLE: Process of manufacturing Trench gate semiconductor device having gate oxide

layer with multiple thicknesses

Full Title Citation Front Review Classification Date Reference Communication Date Reference

5. Document ID: US 6284593 B1

L3: Entry 5 of 7

File: USPT

Sep 4, 2001

US-PAT-NO: 6284593

DOCUMENT-IDENTIFIER: US 6284593 B1

TITLE: Method for shallow trench isolated, contacted well, vertical MOSFET DRAM

Full Title Citation: Front Review Classification Date Reference Classification De

6. Document ID: US 6121089 A

L3: Entry 6 of 7

File: USPT

Sep 19, 2000

US-PAT-NO: 6121089

DOCUMENT-IDENTIFIER: US 6121089 A

TITLE: Methods of forming power semiconductor devices having merged split-well body

regions therein

Full Title Citation Front Review Classification Crate Reference Claims KMC Draw Dr

7. Document ID: US 6078090 A

L3: Entry 7 of 7

File: USPT

Jun 20, 2000

US-PAT-NO: 6078090

DOCUMENT-IDENTIFIER: US 6078090 A

TITLE: Trench-gated Schottky diode with integral clamping diode

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Terms Documents

L2 and trench 7

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